Rev. 2 [12. 2008]



Optical Components

OD9249N

10Gbps PIN-TIA/AGC receiver module

1. DESCRIPTION

OD9249N is a 10Gbps receiver module that incorporates an InGaAs PIN photodiode and an integrated AGC-TIA in a hermetically sealed package. OD9249N adopts compact surface mount package, minimizing the space on PCB. The outline is based on a multi-source agreement (MSA) that defines small footprint coplanar OC-192 receivers.

2. FEATURES

Power supply (TIA): 3.3V High sensitivity: -19.0dBm Typ.

Differential transimpedance: 0.2 to $7.0k\Omega$

Power consumption: 0.2W Typ.

Surface-mount and hermetically sealed package

Small footprint co-planar output

3. APPLICATION

SONET OC-192/SDH STM-64 applications WDM applications

4.OPTICAL AND ELECTRICAL CHARACTERISTICS

 $(\lambda=1550 \text{nm}, \text{Tc} = +25^{\circ}\text{C}, \text{VCC}=+3.3\text{V}, \text{VPD}=+5\text{V}, \text{unless otherwise specified})$

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Wavelength	λ		1250		1620	nm
PIN-PD Responsivity	R_{PD}	λ=1550nm	0.75	0.9		A /XX
		λ=1310nm	0.75	0.85		A/W
Dark Current	ID	$V_{PD}=+5V$			1.0	nA
Maximum Transimpedance	Ztmax	Differential, Pin=0mW		7.0		kΩ
Minimum Transimpedance	Ztmin	Differential, Overload condition		0.2		kΩ
Bandwidth	BW	f3dB,RL=50Ω, Pin=-17dBm	8	9		GHz
Sensitivity	Prmin	10Gbps,NRZ,BER=10 ⁻¹² , PRBS2 ³¹ -1 ,Rext=12dB		-19.0	-18.0	dBm
Overload	Prmax	10Gbps,NRZ,BER=10 ⁻¹² , PRBS2 ³¹ -1 ,Rext=12dB	+2	+3		dBm
Group Delay Deviation	GD	130MHz to 8GHz		± 30	± 50	ps
Output Voltage Swing	Vout	Pin=-17dBm, Differential		230		mV
		Pin>-15dBm, Differential		340		
Supply Current	I_{CC}	Pin=0mW		60	85	mA
Recommended Supply Voltage	V_{CC}	-	+3.1	+3.3	+3.5	V
	V_{PD}		+4.5	+5	+10	V
Power Consumption	P	Pin=0mW		0.20	0.29	W
Electrical Return Loss	ERL	130MHz to 10GHz Diffrential S22			-8	dB
Optical Return Loss	ORL	λ=1550nm			-27	dB

5.ABSOLUTE MAXIMUM RATING

(Tc = ± 25 °C, unless otherwise specified)

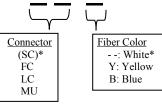
Parameter	Symbol	Rating	Unit
TIA Supply Voltage	V_{CC}	0 to +3.7	V
PD Supply Voltage	V_{PD}	+15	V
Incident Optical Power	Pin	+5.0	dBm
Operating Temparature	Tc	-20 to 85	°C
Stroage Temparature	Tstg	-40 to 85	°C

6. CONNECTOR AND FIBER SPECIFICATIONS

Parameter	Specifications	Unit
Туре	SM	
Mode Field Diameter	10	um
Cladding Diameter	125	um
Jaket Diameter	900	um
Length	1	m
Standard Connector	SC/SPC	

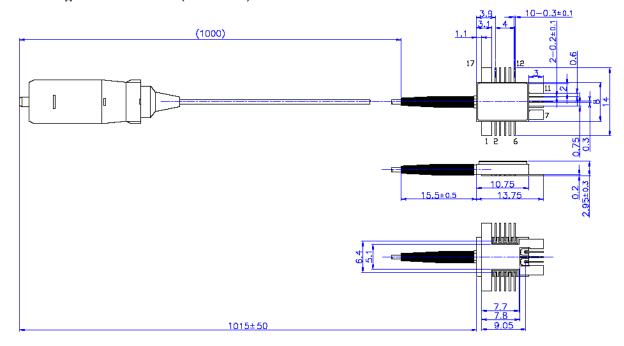
7. ORDERING INFORMATION





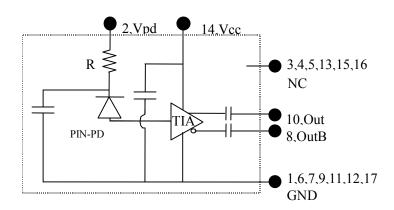
^{* :} Standard. No need to indicate.

8.OUTLINE DRAWING Package No. OD9249N (Unit: mm)



Pin (Connection		
1	Case GND	10	OUT (AC-coupled)
2	Vpd (PIN-PD Bias)	11	Case GND
3	NC	12	Case GND
4	NC	13	NC
5	NC	14	Vcc (TIA Power supply)
6	Case GND	15	NC
7	Case GND	16	NC
8	OUTB(AC-coupled)	17	Case GND
9	Case GND		

9.BLOCK DIAGRAM



SAFETY INFORMATION ON THIS PRODUCT

Caution	The product contains gallium arsenide, GaAs.
	GaAs vapor and powder are hazardous to human health if inhaled, ingested or
GaAs	swallowed.
Product	Do not destory or burn the product.
	Do not crush or chemically dissolve the product.
	Do not put the product in the mouth.
	Observe related laws and company regulations when discarding this product.
	The product should be excluded from general industrial waste or household
	garbage.
Caution	A glass-fiber is attached on the product. Handle with care.
Optical	When the fiber is broken or damaged, handle carefully to avoid injury from
Fiber	the damaged part or fragments.
Attention	Appropriate precautions must be taken to avoid exposure to ESD and EOS
ESD	during handring the product.
sensitive	

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